industrial

GOODRAM Industrial 2.5" SSD S11 MLC silver-gold-diamond

DATASHEET

Version: 1.1
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2,5" Solid State Drive with SATA interface for Industrial Applications

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REVISION HISTORY

VERSION	CHANGES	DATE
1.0	Initial release	03.10.2019
1.1	Logo amendment	16.06.2020

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PRODUCT OVERVIEW

- **Capacity**
  - 4GB up to 512GB
- **SATA Interface**
  - SATA Revision 3.2
  - SATA 1.5Gbs, 3Gbps and 6Gbps interface
- **Flash Memory**
  - Flash Type: Toshiba 15 nm MLC
  - 1pcs to 4pcs of TSOP/BGA flash
- **Performance** Note1
  - Read: up to 550 MB/s
  - Write: up to 490 MB/s
- **Power Consumption** Note2
  - Active mode: < 2650mW
  - Idle mode: < 315mW
  - DEVSLP mode: < 5mW
- **TBW (terabytes written)** Note3
  - 540TBW for 512GB
- **RoHS compliant**
- **MTBF**
  - More than 2,000,000 hours
- **Controller**
  - PS3111-S11
- **Advanced Flash Management**
  - Static and Dynamic Wear Leveling
  - Bad Block Management
  - TRIM
  - SMART
  - NCQ
  - Over-provisioning
  - Firmware update
  - SmartZIP™
- **Low Power Management**
  - DIPM/HIPM Mode
  - DEVSLP Mode (optional)
- **Temperature Range** Note4
  - Operational (Silver): 0 ~+ 70°C
  - Operational (Gold): -25°C ~+ 85°C
  - Operational (Diamond): -40°C ~+ 85°C
  - Storage: -40°C ~ +85°C

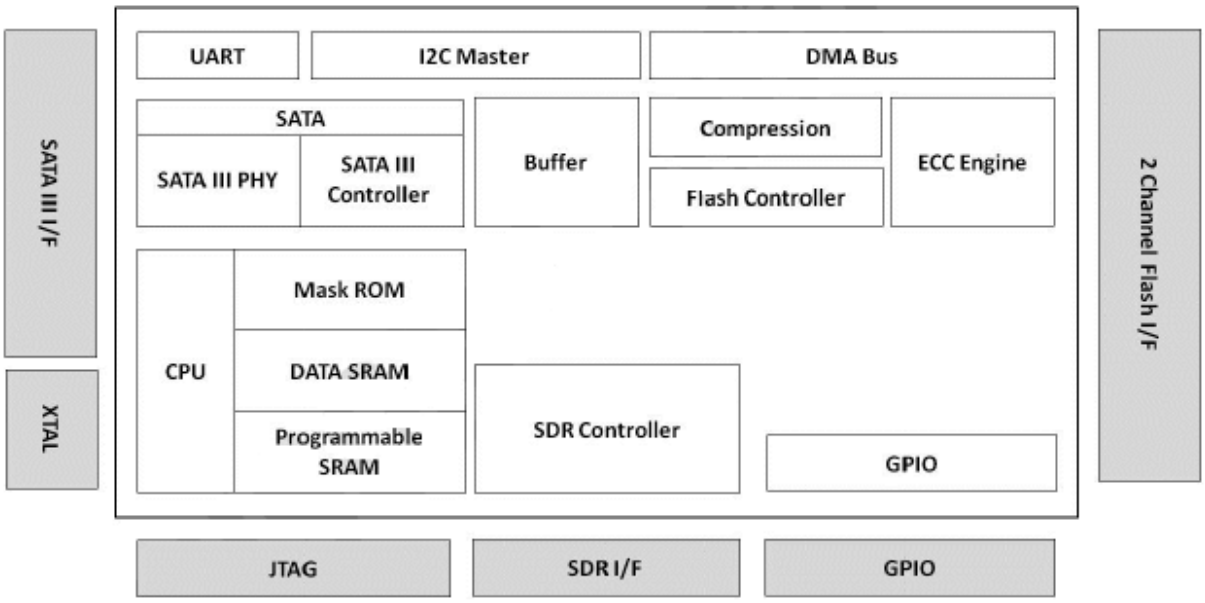
Notes:
1. Measured by CrystalDiskMark v3.0
2. Please see "Power Consumption" for details.
3. Please see "TBW (Terabyte Written)" for details.
4. According to standards IEC-60068-2-1/2/14/38

PRODUCT DETAILS

GENERAL DESCRIPTION

GOODRAM Industrial 2.5'' SSD delivers all the advantages of Flash Drive technology with Serial ATA III interface. It is designed with the form factor of 7-Pin SATA signals and 15-Pin for power segment and could be mounted directly to Host without any effort. The SATA SSD is designed to operate at a maximum operating frequency of 200MHz with 30MHz external crystal. The capacity could provide a wide range up to 512GB and the performance reach up to 550MB/s read as well as 490MB/s write based on Toggle 2.0 MLC (with 32MB SDR cache enabled and measured by CrystalDiskMark). Meanwhile, the power consumption is much lower than traditional Hard Drives.

CONTROLLER BLOCK DIAGRAM



2,5'' SSD Controller Block Diagram

FLASH MANAGEMENT

GOODRAM Industrial 2.5'' MLC SSD utilizes all the state of art technologies to ensure full reliability until the TBW parameter is reached. These technologies include:

Error Correction Code (ECC)

Flash memory cells will deteriorate with use, which might generate random bit errors in the stored data. Thus, SSD drive applies the LDPC (Low Density parity Check) of ECC algorithm, which can detect and correct errors occur during read process, ensure data been read correctly, as well as protect data from corruption.

Wear Leveling

NAND Flash devices can only undergo a limited number of program/erase cycles, and in most cases, the flash media are not used evenly. If some area get updated more frequently than others, the lifetime of the device would be reduced significantly. Thus, Wear Leveling technique is applied to extend the lifespan of NAND Flash by evenly distributing write and erase cycles across the media. Product has advanced Wear Leveling algorithm, which can efficiently spread out the flash usage through the whole flash media area. Moreover, by implementing both dynamic and static Wear Leveling algorithms, the life expectancy of the NAND Flash is greatly improve.

Bad Block Management

Bad blocks are blocks that include one or more invalid bits, and their reliability is not guaranteed. Blocks that are identified and marked as bad by the manufacturer are referred to as "Initial Bad Blocks". Bad blocks that are developed during the lifespan of the flash are named "Later Bad Blocks". We implement an efficient bad block management algorithm to detect the factory-produced bad blocks and manages any bad blocks that appear with use. This practice further prevents data being stored into bad blocks and improves the data reliability.

TRIM

TRIM is a feature which helps improve the read/write performance and speed of solid-state drives (SSD). Unlike hard disk drives (HDD), SSDs are not able to overwrite existing data, so the available space gradually becomes smaller with each use. With the TRIM command, the operating system can inform the SSD which blocks of data are no longer in use and can be removed permanently. Thus, the SSD will perform the erase action, which prevents unused data from occupying blocks all the time.

SMART

SMART, an acronym for Self-Monitoring, Analysis and Reporting Technology, is an open standard that allows a hard disk drive to automatically detect its health and report potential failures. When a failure is recorded by SMART, users can choose to replace the drive to prevent unexpected outage or data loss. Moreover, SMART can inform users of impending failures while there is still time to perform proactive actions, such as copy data to another device.

Over-Provision

Over Provisioning refers to the inclusion of extra NAND capacity in a SSD, which is not visible and cannot be used by users. With Over Provisioning, the performance and IOPS (Input/Output Operations per Second) is improved by providing the controller additional space to manage P/E cycles, which enhances the reliability and endurance as well. Moreover, the write amplification of the SSD becomes lower when the controller writes data to the flash.

Firmware Upgrade

Firmware can be considered as a set of instructions on how the device communicates with the host. Firmware will be upgraded when new features are added, compatibility issues are fixed, or read/write performance gets improved.

SmartZIP™

Write data to the NAND Flash costs time. To improve the write speed performance, controller launches with compression technique – SmartZIP™. Whether a file could be compressed or not depending on the file type, for file types have redundancy data pattern, through our embedded encode engine, we could reduce the amount of data that is actually written to the Flash. Comparing to the SSD without compression, write efficiency is raised and the SSD endurance is also improved since Flash could be benefit from less data written for longer SSD lifetime.

ADDITIONAL FEATURES

Low Power Management (DIPM/HIPM Mode)

SATA interfaces contain two low power management states for power saving: Partial and Slumber modes. For Partial mode, the device has to resume to full operation within 10 microseconds, whereas the device will spend 10 milliseconds to become fully operational in the Slumber mode. SATA interfaces allow low power modes to be initiated by Host (HIPM, Host Initiated Power Management) or Device (DIPM, Device Initiated Power Management). As for HIPM, Partial or Slumber mode can be invoked directly by the software. For DIPM, the device will send requests to enter Partial or Slumber mode.

DEVSLP Mode (optional)

With the increasing need of aggressive power/battery life, SATA interfaces include a new feature, Device Sleep (DEVSLP) mode, which helps further reduce the power consumption of the device. DEVSLP enables the device to completely power down the device PHY and other sub-systems, making the device reach a new level of lower power operation. The DEVSLP does not specify the exact power level a device can achieve in the DEVSLP mode, but the power usage can be dropped down to 5mW or less.

Power Loss Protection: Flushing Mechanism

Power Loss Protection is a mechanism to prevent data loss during unexpected power failure. DRAM is a volatile memory and frequently used as temporary cache or buffer between the controller and the NAND flash to improve the SSD performance. However, one major concern of the DRAM is that it is not able to keep data during power failure. Accordingly, the controller applies the Guaranteed Flush Technology, which requests the controller to transfer data to the cache. For the used controller, SDR performs as a cache, and its sizes include up to 32MB. Only when the data is fully committed to the NAND flash will the controller send acknowledgement (ACK) to the host. Such implementation can prevent false-positive performance and the risk of power cycling issues.
Additionally, it is critical for a controller to shorten the time the in-flight data stays in the cache. Thus, the controller applies an algorithm to reduce the amount of data resides in the cache to provide a better performance. This SmartCacheFlush technology allows incoming data to only have a "pit stop" in the cache and then move to the NAND flash at once. If the flash is jammed due to particular file sizes (random 4K), the cache will be treated as an "organizer", consolidating incoming data into groups before written into the flash to improve write amplification. In sum, with this Flush Management, the controller proves to provide the reliability required by consumer, industrial, and enterprise-level application.

Advanced Device Security Features (Secure Erase, Write Protect)

Secure Erase is a standard ATA command and will write all "0xFF" to fully wipe all the data on hard drives and SSDs. When this command is issued, the SSD controller will empty its storage blocks and return to its factory default settings. When a SSD contains too many bad blocks and data are continuously written in, then the SSD might not be used anymore. Thus, Write Protect is a mechanism to prevent data from being written in and protect the accuracy of data that are already stored in the SSD.

PRODUCT ORDERING INFORMATION

PN	Type	Capacity	Technology	Temp range	Grade
RUS27M004S3SB-P11TH5	2,5" SATA SSD	4GB	MLC	0~70°C	silver
RUS27M008S3SB-P11TH5	2,5" SATA SSD	8GB	MLC	0~70°C	silver
RUS27M016S3SB-P11TH5	2,5" SATA SSD	16GB	MLC	0~70°C	silver
RUS27M030S3SB-P11TH5	2,5" SATA SSD	30GB	MLC	0~70°C	silver
RUS27M032S3SB-P11TH5	2,5" SATA SSD	32GB	MLC	0~70°C	silver
RUS27M060S3SB-P11TH5	2,5" SATA SSD	60GB	MLC	0~70°C	silver
RUS27M064S3SB-P11TH5	2,5" SATA SSD	64GB	MLC	0~70°C	silver
RUS27M120S3SB-P11TH5	2,5" SATA SSD	120GB	MLC	0~70°C	silver
RUS27M128S3SB-P11TH5	2,5" SATA SSD	128GB	MLC	0~70°C	silver
RUS27M240S3SB-P11TH5	2,5" SATA SSD	240GB	MLC	0~70°C	silver
RUS27M256S3SB-P11TH5	2,5" SATA SSD	256GB	MLC	0~70°C	silver
RUS27M480S3SB-P11TH5	2,5" SATA SSD	480GB	MLC	0~70°C	silver
RUS27M512S3SB-P11TH5	2,5" SATA SSD	512GB	MLC	0~70°C	silver
RUS27M004S3GB-P11TH5	2,5" SATA SSD	4GB	MLC	-25~85°C	gold
RUS27M008S3GB-P11TH5	2,5" SATA SSD	8GB	MLC	-25~85°C	gold
RUS27M016S3GB-P11TH5	2,5" SATA SSD	16GB	MLC	-25~85°C	gold
RUS27M030S3GB-P11TH5	2,5" SATA SSD	30GB	MLC	-25~85°C	gold
RUS27M032S3GB-P11TH5	2,5" SATA SSD	32GB	MLC	-25~85°C	gold
RUS27M060S3GB-P11TH5	2,5" SATA SSD	60GB	MLC	-25~85°C	gold
RUS27M064S3GB-P11TH5	2,5" SATA SSD	64GB	MLC	-25~85°C	gold
RUS27M120S3GB-P11TH5	2,5" SATA SSD	120GB	MLC	-25~85°C	gold
RUS27M128S3GB-P11TH5	2,5" SATA SSD	128GB	MLC	-25~85°C	gold
RUS27M240S3GB-P11TH5	2,5" SATA SSD	240GB	MLC	-25~85°C	gold
RUS27M256S3GB-P11TH5	2,5" SATA SSD	256GB	MLC	-25~85°C	gold
RUS27M480S3GB-P11TH5	2,5" SATA SSD	480GB	MLC	-25~85°C	gold
RUS27M512S3GB-P11TH5	2,5" SATA SSD	512GB	MLC	-25~85°C	gold
RUS27M004S3DB-P11TH5	2,5" SATA SSD	4GB	MLC	-40~85°C	diamond
RUS27M008S3DB-P11TH5	2,5" SATA SSD	8GB	MLC	-40~85°C	diamond
RUS27M016S3DB-P11TH5	2,5" SATA SSD	16GB	MLC	-40~85°C	diamond
RUS27M030S3DB-P11TH5	2,5" SATA SSD	30GB	MLC	-40~85°C	diamond
RUS27M032S3DB-P11TH5	2,5" SATA SSD	32GB	MLC	-40~85°C	diamond
RUS27M060S3DB-P11TH5	2,5" SATA SSD	60GB	MLC	-40~85°C	diamond
RUS27M064S3DB-P11TH5	2,5" SATA SSD	64GB	MLC	-40~85°C	diamond
RUS27M120S3DB-P11TH5	2,5" SATA SSD	120GB	MLC	-40~85°C	diamond
RUS27M128S3DB-P11TH5	2,5" SATA SSD	128GB	MLC	-40~85°C	diamond
RUS27M240S3DB-P11TH5	2,5" SATA SSD	240GB	MLC	-40~85°C	diamond
RUS27M256S3DB-P11TH5	2,5" SATA SSD	256GB	MLC	-40~85°C	diamond
RUS27M480S3DB-P11TH5	2,5" SATA SSD	480GB	MLC	-40~85°C	diamond
RUS27M512S3DB-P11TH5	2,5" SATA SSD	512GB	MLC	-40~85°C	diamond

PERFORMANCE AND POWER CONSUMPTION

Capacity	Flash Structure	Performance		Power Consumption			
		CrystalDiskMark		Read (mW)	Write (mW)	Idle (mW)	DEVSLP (mW)
		Read (MB/s)	Write (MB/s)				
4GB	4GB x 1, TSOP	160	50	1120	1150	290	4.9
	4GB x 1, TSOP	300	50	970	900	294	4.9
8GB	8GB x 1, TSOP	165	90	1150	1180	294	4.9
	8GB x 1, TSOP	320	105	980	910	294	4.9
16GB	16GB x 1, TSOP	320	84	1180	1200	315	4.9
30/32GB	16GB x 2, TSOP	550	160	1200	1280	290	4.9
60/64GB	16GB x 4, TSOP	550	310	1200	1320	287	4.9
120/128GB	64GB x 2, BGA	550	465	1250	1600	285	4.9
	32GB x 4, BGA	550	465	1280	1700	285	4.9
	32GB x 4, TSOP	550	465	1050	1650	285	4.9
240/256GB	64GB x 4, BGA	550	490	1350	2600	285	4.9
	32GB x 4, TSOP	550	465	1065	1655	285	4.9
480/512GB	128GB x 4, BGA	550	490	1500	2650	295	4.9
	128GB x 4, TSOP	550	465	1615	1960	295	4.9

NOTES:
1. The performance was measured using CrystalDiskMark with SATA 6Gbps host.
2. Samples were built using Toshiba 15 nm MLC NAND flash.
3. Performance may differ according to flash configuration and platform.
4. The table above is for reference only. The criteria for MP (mass production) and for accepting goods shall be discussed based on different flash configuration.

SUPPLY VOLTAGE

PARAMETER	RATING
Operating voltage	5V +/- 5%

TBW

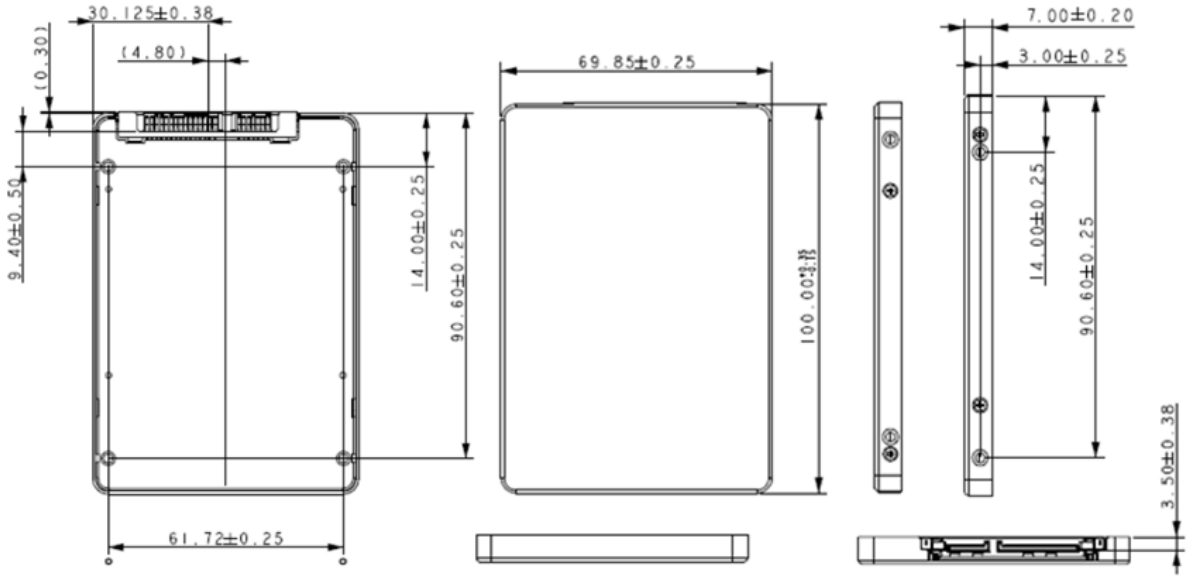
Capacity	Flash Structure	TBW
4GB	4GB x 1, TSOP	1
8GB	8GB x 1, TSOP	3
16GB	16GB x 1, TSOP	6
30/32GB	16GB x 2, TSOP	13
60/64GB	64GB x 4, TSOP	30
120/128GB	64GB x 2, BGA	87
	32GB x 4, BGA	
240/256GB	64GB x 4, BGA	198
480/512GB	128GB x 4, BGA	540

NOTES:

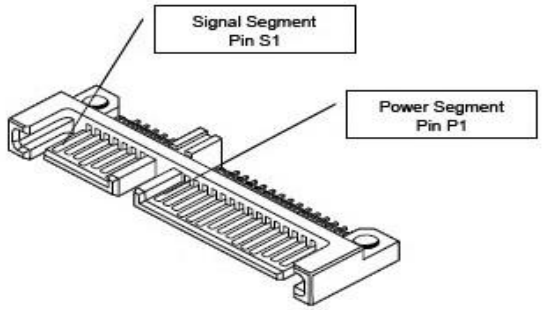
1. Samples were built using Toshiba 15 nm MLC NAND flash.
2. The test followed JEDEC219A client endurance workload.
3. TBW may differ according to flash configuration and platform.
4. The endurance of SSD could be estimated based on user behaviour, NAND endurance cycles, and write amplification factor. It is not guaranteed by flash vendor.

PHYSICAL DIMENSION

Dimension: 100.00mm (L) x 69.85mm (W) x 7.00mm (H)



PIN ASSIGNMENT AND DESCRIPTIONS



Signal Segment Pin Assignment and Descriptions

Pin Number	Function
S1	GND
S2	A+ (Differential Signal Pair A)
S3	A – (Differential Signal Pair A)
S4	GND
S5	B – (Differential Signal Pair B)
S6	B+ (Differential Signal Pair B)
S7	GND

Power Segment Pin Assignment and Descriptions

Pin Number	Function
P1	Not Used (3.3V)
P2	Not Used (3.3V)
P3	DEVSLP
P4	GND
P5	GND
P6	GND
P7	5V pre-charge
P8	5V
P9	5V
P10	GND
P11	Reserved
P12	GND
P13	Not Used (12V pre-charge)
P14	Not Used (12V)
P15	Not Used (12V)

SUPPORTED ATA COMMAND LIST

Op-Code		Command Description	Op-Code			Command Description
00h		NOP	C9h			Read DMA without Retry
06h		Data Set Management	CAh			Write DMA
10h-1Fh		Recalibrate	CBh			Write DMA without Retry
20h		Read Sectors	CEh			Write Multiple FUA EXT
21h		Read Sectors without Retry	E0h			Standby Immediate
24h		Read Sectors EXT	E1h			Idle Immediate
25h		Read DMA EXT	E2h			Standby
27h		Read Native Max Address EXT	E3h			Idle
29h		Read Multiple EXT	E4h			Read Buffer
2Fh		Read Log EXT	E5h			Check Power Mode
30h		Write Sectors	E6h			Sleep
31h		Write Sectors without Retry	E7h			Flush Cache
34h		Write Sectors EXT	E8h			Write Buffer
35h		Write DMA EXT	E9h			READ BUFFER DMA
37h		Set Native Max Address EXT	EAh			Flush Cache EXT
38h		CFA Write Sectors Without Erase	EBh			Write Buffer DMA
39h		Write Multiple EXT	ECh			Identify Device
3Dh		Write DMA FUA EXT	EFh			Set Features
3Fh		Write Long EXT	EFh	02h		Enable volatile write cache
40h		Read Verify Sectors	EFh	03h		Set transfer mode
41h		Read Verify Sectors without Retry	EFh	05h		Enable the APM feature set
42h		Read Verify Sectors EXT	EFh	10h		Enable use of SATA features et
44h		Zero EXT	EFh	10h	02h	Enable DMA Setup FIS Auto-Activate optimization
45h		Write Uncorrectable EXT	EFh	10h	03h	Enable Device-initiated interface power state (DIPM) transitions
47h		Read Log DMA EXT	EFh	10h	06h	Enable Software Settings Preservation (SSP)
57h		Write Log DMA EXT	EFh	10h	07h	Enable Device Automatic Partial to Slumber transitions
60h		Read FPDMA Queued	EFh	10h	09h	Enable Device Sleep
61h		Write FPDMA Queued	EFh	55h		Disable read look-ahead
70h-7Fh		Seek	EFh	66h		Disable reverting to power-on defaults
90h		Execute Device Diagnostic	EFh	82h		Disable volatile write cache
91h		Initialize Device Parameters	EFh	85h		Disable the APM feature set
92h		Download Microcode	EFh	90h		Disable use of SATA feature set
93h		Download Microcode DMA	EFh	90h	02h	Disable DMA Setup FIS Auto-Activate optimization
B0h		SMART	EFh	90h	03h	Disable Device-initiated interface power state (DIPM) transitions
B0h	D0h	SMART READ DATA	EFh	90h	06h	Disable Software Settings Preservation (SSP)
B0h	D1h	SMART READ ATTRIBUTE THRESHOLDS	EFh	90h	07h	Disable Device Automatic Partial to Slumber transitions
B0h	D2h	SMART ENABLE/DISABLE ATTRIBUTE AUTOSAVE	EFh	90h	09h	Disable Device Sleep

B0h	D3h	SMART SAVE ATTRIBUTE VALUES	EFh	AAh	Enable read look-ahead
B0h	D4h	SMART EXECUTE OFF-LINE IMMEDIATE	EFh	CCh	Enable reverting to power-on defaults
B0h	D5h	SMART READ LOG	F1h		Security Set Password
B0h	D6h	SMART WRITE LOG	F2h		Security Unlock
B0h	D8h	SMART ENABLE OPERATIONS	F3h		Security Erase Prepare
B0h	D9h	SMART DISABLE OPERATIONS	F4h		Security Erase Unit
B0h	DAh	SMART RETURN STATUS	F5h		Security Freeze Lock
B0h	DBh	SMART ENABLE/DISABILE AUTOMATIC OFF-LINE	F6h		Security Disable Password
B1h		Device Configuration	F8h		Read Native Max Address
B4h		Sanitize	F9h		Set Max Address
C4h		Read Multiple	F9h	01h	SET MAX SET PASSWORD
C5h		Write Multiple	F9h	02h	SET MAXLOCK
C6h		Set Multiple Mode	F9h	03h	SET MAX UNLOCK
C8h		Read DMA	F9h	04h	SET MAX FREEZE LOCIK

STANDARDS & REFERENCES

The following table is to list out the standards that have been adopted for designing the product.

STANDARD USED	ACRONYM/SOURCE
RoHS	Restriction of Hazardous Substances Directive; please contact us for further information
Serial ATA Revision 3.2	http://www.sata-io.org
ATA-8 spec	http://www.t13.org
CE	Consumer electronics certification; please contact us for further information.

SAFETY PRECAUTIONS

Do not bend, crush, drop or place heavy objects on top of the Product. Do not use tweezers, pliers or similar items that could damage the Product. Take particular care when inserting or removing the Product. Stop using the Product when the Product does not work properly. Failure to follow these instructions could result in fire, damage to the Product and/or other property, and/or personal injury including burns and electric shock.

Keep out of reach of small children. Accidental swallowing may cause suffocation or injury. Contact a doctor immediately if you suspect a child has swallowed the Product.

Do not directly touch the interface pins, put them in contact with metal, strike them with hard objects or cause them to short. Do not expose to static electricity.

Do not disassemble or modify the Product. This may cause electric shock, damage to the Product or fire.

NOTES ON USAGE

The Product contains nonvolatile semiconductor memory. Do not use the Product in accordance with a method of usage other than that written in the manual. This may cause the destruction or loss of data.

To protect against accidental data loss, you should back up your data frequently on more than one type of storage media. Wilk Elektronik S.A. assumes no liability for destruction or loss of data recorded on the Card for any reason.

When used over a long period of time or repeatedly, the reading, writing and deleting capabilities of the Product will eventually fail, and the performance speed of the Product may decrease below the original speed specific to the Product's applicable class.

If the Product is to be transferred or destroyed, note that the data it contained may still be recoverable unless it is permanently deleted by third-party deletion software or similar means beforehand.

Product is intended for use in general electronics applications and selected industrial applications and any other specific applications as expressly stated in this document. Product is neither intended nor warranted for use in equipment or systems where failure may cause loss of human life, bodily injury, serious property damage or serious public impact ("Unintended Use"). Unintended Use includes, without limitation, equipment used in nuclear facilities, equipment used in the aerospace industry, medical equipment or equipment used to control combustions or explosions. Do not use Product for Unintended Use unless specifically permitted in this document.

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